

FORM PTO-1449 (Colb)	ATTY DOCKET NO. 206,407	SERIAL NUMBER 10/750,716
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION STATEMENT	APPLICANT Yossi SHACHAM-DIAMAND et al.	EXAMINER Klemanski
OCT 04 2004 U.S. PATENT AND TRADEMARK OFFICE	FILING DATE January 2, 2004	GROUP ART UNIT 1755

U.S. PATENT DOCUMENTS

Examiner's Initials		DOCUMENT NO.	DATE	NAME	CLASS	SUB	FILING DATE
JKL	AA	5,695,810	12-1997	Dubin, et al.	438	643	
JKL	AB	5,674,787	10-1997	Zhao, et al.	438	627	
JKL	AC	4,209,331	06-1980	Kukanskis, et al.	106	1.23	
JKL	AD	4,150,171	04-1979	Feldstein	427	558	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB	TRANSLATION
	AE						
	AF						

OTHER ART (Including Author, Bills, Pertinent Pages, Etc.)

JKL	AG	P.C. Andricacos, Damascene Copper Electroplating for Chip Interconnect, IBM J. Res. Develop 42 (1998) 567-573, no month available.
JKL	AH	Y. Shacham-Diamond, V. Dubin, and M. Angyal, Copper Electroless deposition for ULSI, Thin Solid Films, 262, (1995) 93-103, no month available.
JKL	AI	Vashkjalis A., Demontaine O. Study of Cu electroless deposition process using NaBH4 as a reducing agent, Lithuanian Academy of Sciences publication, series B, Vol. 4(95), pp.11-16, 1976, no month available.
JKL	AJ	Molenaar A., J. of the Electrochem. Soc., 1982 Vol. 129, N 9, p.1917-1921, no month available.
JKL	AK	Shalkauskas M., Vashkjalis A. Electroless deposition of metals on plastics, L., J. Chemistry, 1985, pp. 95-113, no month available.
JKL	AL	Tetsuya Ogura, M. Malcomson, Q. Fernando, Mechanism of Copper Deposition in Electroless plating, Langmuir 1990, 6, pp.1709-1710, no month available.

EXAMINER: Helen Klemanski DATE CONSIDERED: 3-14-06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 (Colb)	ATTY DOCKET NO. 206,407	SERIAL NUMBER 10/750,716
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION STATEMENT	APPLICANT Yossi SHACHAM-DIAMAND et al.	EXAMINER <i>(initials)</i> <i>Klemanski</i>
	FILING DATE January 2, 2004	GROUP ART UNIT <i>1755</i>

U.S. PATENT DOCUMENTS

Examiner's Initials		DOCUMENT NO.	DATE	NAME	CLASS	SUB	FILING DATE
	AA						
	AB						
	AC						
	AD						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB	TRANS- LATION
	AE						
	AF						

OTHER ART (Including Author, Bills, Pertinent Pages, Etc.)

<i>CH</i>	AG	F.P. Pearlstein and R.F. Weightman, Electroless Deposition of Silver Using Dimethylamine Borane, Plating, February 1974, pp.154-157.
<i>CH</i>	AH	Y. Shacham-Diamond, and V. Dubin, J. of Microelectronics Engineering, 33, pp. 47-58, 1997 .
<i>CH</i>	AI	Yosi Shacham-Diamond and Sergey Lopatin, Journal of Microelectronics Engineering, Vol. 37/38, pp. 77-88, 1997, no month available .
<i>CH</i>	AJ	E. Gileadi, Electrode Kinetics, VCH Publishers, New York 1993, no month available .
<i>CH</i>	AK	E. Podlaha and D. Landolt, A Mathematical Model Describing the Electrodeposition of Ni-Mo Alloys, J.of the Electrochem. Soc., Vol. 143, pp.893-899, 1996, no month available .
<i>CH</i>	AL	E. Podlaha and D. Landolt, Molybdenum Alloys with Nickel, Cobalt and Iron, J.of the Electrochem. Soc., Vol. 144, pp.1672-1680, 1997, no month available .
EXAMINER: <i>Helene Klemanski</i>		DATE CONSIDERED: 3-14-06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 (Colb)	ATTY DOCKET NO. 206,407	SERIAL NUMBER 10/750,716
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION STATEMENT	APPLICANT Yossi SHACHAM-DIAMAND et al.	EXAMINER <i>(initials)</i> <i>KlemanSKI</i>
	FILING DATE January 2, 2004	GROUP ART UNIT <i>1752 1755</i>

U.S. PATENT DOCUMENTS

Examiner's Initials		DOCUMENT NO.	DATE	NAME	CLASS	SUB	FILING DATE
	AA						
	AB						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB	TRANS- LATION
	AC						
	AD						

OTHER ART (Including Author, Bills, Pertinent Pages, Etc.)

<i>(initials)</i>	AE	E. Podlaha and D. Landolt, An Experimental Investigation of Ni-Mo Alloys, J. of the Electrochem. Soc., Vol. 143, pp. 885-892, 1996, no month available.
<i>(initials)</i>	AF	Y.Shacham-Diamond and Y.Sverdlov, Electroless Cu alloys for ULSI applications, in Proceedings of the Advanced Metallization Conference 2001 (AMC 2001), p.67-72, <i>Montreal, Canada</i> , 8-11 October 2001.
<i>(initials)</i>	AG	Y.Shacham-Diamond, A.Inberg, Y.Sverdlov and N.Croitoru, Electroless Silver and Silver with Tungsten Thin Films for Microelectronics and Microelectromechanical System Applications, J.of the Electrochemical Society, 147 (9) 3345-3349 (2000) 1/2000.
<i>(initials)</i>	AH	K.M. Gorbunova, A.A. Nikiforova, G.A. Sadakov, V.P. Moiseev, M.V. Ivanov, "Physical-chemical origins of chemical cobalt deposition", "Science" publication, Moscow, pp.195-201, 1974, no month available.
<i>(initials)</i>	AI	F.Ajogin, M.Belenki, I.Gall, "Galvanotechnique", "Metallurgy" publication, Moscow, pp.170-178, 538-540, 1987, no month available.
<i>(initials)</i>	AJ	Y.Shacham-Diamond, A.Inberg, Y.Sverdlov, V.Bogush, N.Croitoru, H.Moscovich, A.Freeman, Electroless process for micro-and nanoelectronics, J.Electrochimica Acta 48 (2003) 2987-2996, no month available.

EXAMINER:

Helene KlemanSKI DATE CONSIDERED: *3-14-06*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.